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TI Preparation of ceramic fiber heat-insulation board
IN Lu, Chenghui; Liu, Chao; Li, Jingyou; Zhang, Yingxin
PA Shandong Luyang Co., Ltd., Peop. Rep. China
SO Faming Zhuanli Shenqing Gongkai Shuomingshu, 6 pp.
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DT Patent
LA Chinese
IC ICM C04B014-38
ICS C04B028-00; C04B024-40; E04B001-76
CC 57-2 (Ceramics)
Section cross-reference(s): 38

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PI	CN 1385388 /	A	20021218	CN 2002-120854	20020606
PRAI	CN 2002-120854		20020606		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
CN 1385388	ICM	C04B014-38
	ICS	C04B028-00; C04B024-40; E04B001-76
CN 1385388	ECLA	C04B028/00

AB The title board is composed of ceramic fiber, inorg. binder, organic binder and additive at ratio of 40-60:20- 30:0.5-1.5:20-30. The organic binder may be from one or more of polyacrylamide, cationic starch or CM-cellulose; the inorg. binder from one or more of cement, silica sol, alumina sol and Na₂SiO₃; and the additive from silica powder, puffed silica powder, perlite powder and silicon powder. The board is prepared by mixing the raw material, pressing, and drying at 100-150°.

ST heat insulation board ceramic fiber

IT Silica gel, uses

RL: NUU (Other use, unclassified); USES (Uses)

(additive containing; for preparation of ceramic fiber heated board)

IT **Cement**